

ABSTRACT

Disclosed is an epoxy resin composition suitable for sealing a semiconductor, comprising an epoxy resin (A), a hardener(B), an inorganic filler(C), and a phosphoric acid ester compound(D), an amount of the inorganic filler (C) contained being 80% by weight relative to the composition.

With this constitution, a semiconductor sealing epoxy resin composition excellent in flame retardancy, formability, reliability and solder heat resistance is obtained without an essential need to use a halogen-based flame retardant or an antimony-based flame retardant.